## **LY T676**

### **TOPLED®**

TOPLED, SMT LED with integrated reflector. With our great experience in SMT LED we are able to offer a high quality product for all kind of applications.









### **Applications**

- Cluster, Button Backlighting
- Electronic Equipment

- Interior Illumination (e.g. Ambient Map)
- White Goods

### **Features**

- Package: white PLCC-2 package, colorless clear resin
- Chip technology: InGaAIP
- Typ. Radiation: 120° (Lambertian emitter)
- Color:  $\lambda_{dom} = 587 \text{ nm}$  (• yellow)
- Corrosion Robustness Class: 3B
- Qualifications: AEC-Q102 Qualified
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM)



Ordering Information			
Туре	Luminous Intensity 1)  I <sub>F</sub> = 20 mA  I <sub>v</sub>	Ordering Code	
LY T676-R1T1-26	112 355 mcd	Q65112A2199	



### LY T676

Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	$T_{op}$	min. max.	-40 °C 100 °C
Storage Temperature	$T_{stg}$	min. max.	-40 °C 100 °C
Junction Temperature	T <sub>j</sub>	max.	125 °C
Forward current T <sub>S</sub> = 25 °C	I <sub>F</sub>	max.	30 mA
Forward current pulsed $t \le 10 \text{ µs}$ ; D = 0.005 ; T <sub>s</sub> = 25 °C	I <sub>F pulse</sub>	max.	200 mA
Reverse voltage <sup>2)</sup> T <sub>S</sub> = 25 °C	$V_R$	max.	12 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM)	$V_{ESD}$		2 kV



## **Characteristics**

 $I_F = 20$  mA;  $T_S = 25$  °C

Parameter	Symbol	Values	
Peak Wavelength	$\lambda_{\sf peak}$	typ.	588 nm
Dominant Wavelength <sup>3)</sup> I <sub>F</sub> = 20 mA	$\lambda_{dom}$	min. typ. max.	580 nm 587 nm 595 nm
Spectral Bandwidth at 50% I <sub>rel,max</sub>	Δλ	typ.	15 nm
Viewing angle at 50% $\rm I_{_{ m V}}$	2φ	typ.	120 °
Forward Voltage <sup>4)</sup> I <sub>F</sub> = 20 mA	$V_{F}$	min. typ. max.	1.90 V 2.00 V 2.40 V
Reverse current <sup>2)</sup> V <sub>R</sub> = 12 V	I <sub>R</sub>	typ. max.	0.01 μA 10 μA
Temperature Coefficient of Peak Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda peak}$	typ.	0.13 nm / K
Real thermal resistance junction/ambient 5)6)	$R_{ ext{thJA real}}$	max.	500 K / W
Real thermal resistance junction/solderpoint 5)	$R_{ ext{thJS real}}$	max.	280 K / W



# **Brightness Groups**

Group	Luminous Intensity <sup>1)</sup> $I_F = 20 \text{ mA}$ min. $I_V$	Luminous Intensity. 1)  I <sub>F</sub> = 20 mA  max. I <sub>v</sub>	Luminous Flux <sup>7)</sup> $I_F = 20 \text{ mA}$ typ. $\Phi_V$
R1	112 mcd	140 mcd	380 mlm
R2	140 mcd	180 mcd	480 mlm
S1	180 mcd	224 mcd	610 mlm
S2	224 mcd	280 mcd	760 mlm
T1	280 mcd	355 mcd	950 mlm

# **Wavelength Groups**

Group	Dominant Wavelength $^{3)}$ $I_F = 20 \text{ mA}$ min. $\lambda_{\text{dom}}$	Dominant Wavelength $^{3)}$ $I_F = 20 \text{ mA}$ $max.$ $\lambda_{dom}$
2	580 nm	583 nm
3	583 nm	586 nm
4	586 nm	589 nm
5	589 nm	592 nm
6	592 nm	595 nm



# **Group Name on Label**

Example: R1-2
Brightness Wavelength

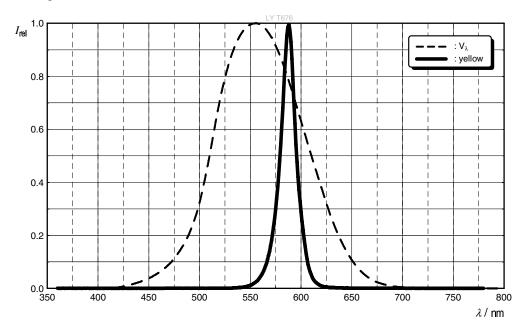
2

R1



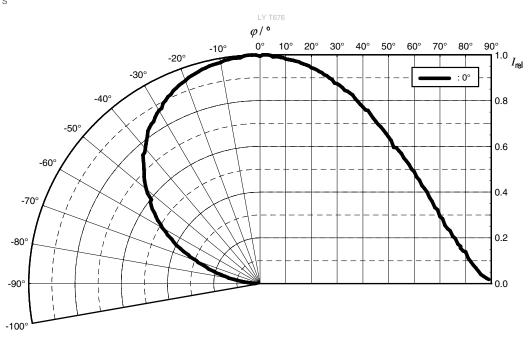
## Relative Spectral Emission 7)

$$I_{rel}$$
 = f ( $\lambda$ );  $I_{F}$  = 20 mA;  $T_{S}$  = 25 °C



## Radiation Characteristics 7)

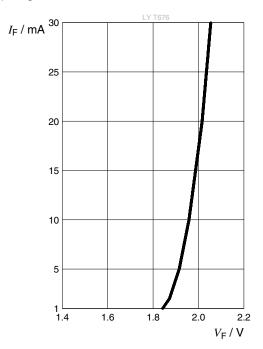
$$I_{rel} = f(\phi); T_S = 25 \, ^{\circ}C$$





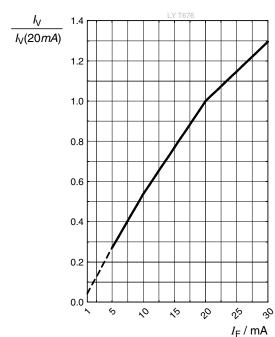
## Forward current 7)

$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



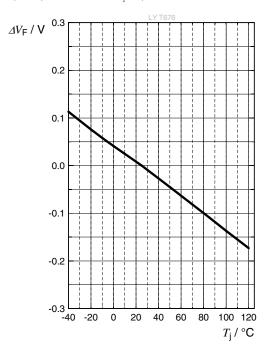
# Relative Luminous Intensity 7), 8)

$$I_{v}/I_{v}(20 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$$



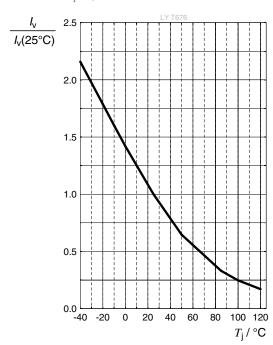
### Forward Voltage 7)

$$\Delta V_{_F} = V_{_F} - V_{_F} (25~^{\circ}C) = f(T_{_j}); \ I_{_F} = 20~mA$$



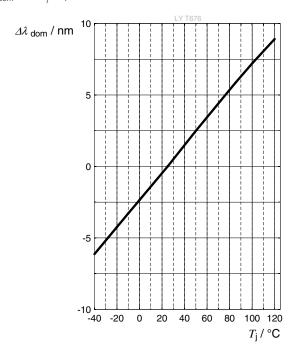
## Relative Luminous Intensity 7)

$$I_{v}/I_{v}(25 \text{ °C}) = f(T_{j}); I_{F} = 20 \text{ mA}$$



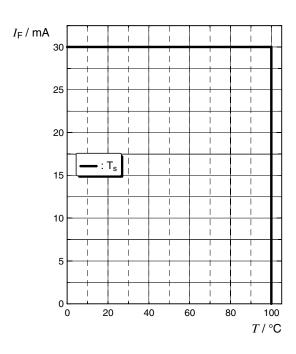
# Dominant Wavelength 7)

$$\lambda_{dom} = f(T_j); I_F = 20 \text{ mA}$$



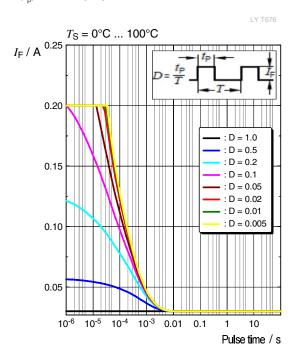
## Max. Permissible Forward Current

 $I_F = f(T)$ 



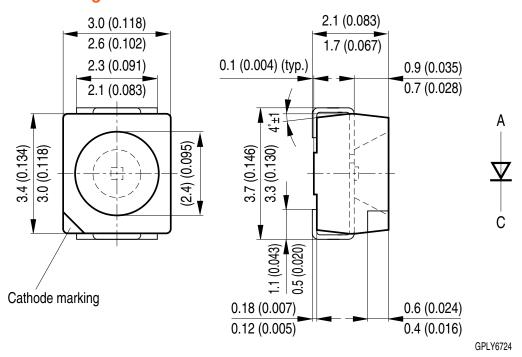
# Permissible Pulse Handling Capability

 $I_F = f(t_p)$ ; D: Duty cycle





## **Dimensional Drawing** 9)



### **Further Information:**

**Approximate Weight:** 34.0 mg

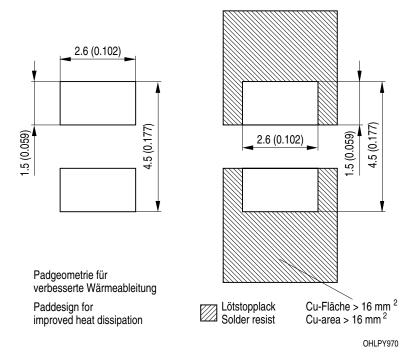
Corrosion test: Class: 3B

Test condition:  $40^{\circ}$ C / 90 % RH / 15 ppm H<sub>2</sub>S / 14 days (stricter than IEC

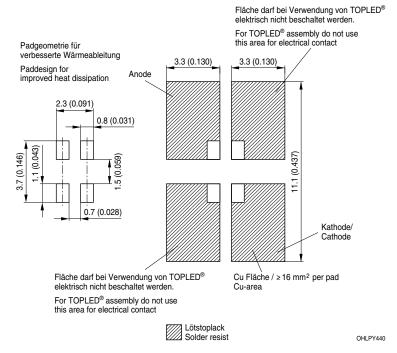
60068-2-43)



### Recommended Solder Pad 9)



### Recommended Solder Pad 9)

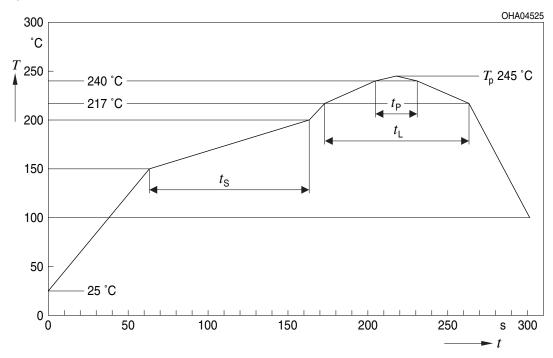


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



## **Reflow Soldering Profile**

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



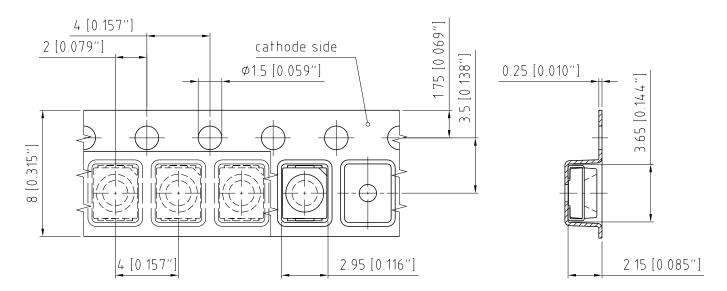
Profile Feature	Symbol	Symbol Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*)	'		2	3	K/s
25 °C to 150 °C					
Time t <sub>s</sub>	$t_s$	60	100	120	S
$T_{Smin}$ to $T_{Smax}$					
Ramp-up rate to peak*)			2	3	K/s
$T_{Smax}$ to $T_{P}$					
Liquidus temperature	$T_L$		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	$T_{P}$		245	260	°C
Time within 5 °C of the specified peak	t <sub>P</sub>	10	20	30	S
temperature T <sub>P</sub> - 5 K					
Ramp-down rate*			3	6	K/s
T <sub>P</sub> to 100 °C					
Time				480	S
25 °C to T <sub>P</sub>					

All temperatures refer to the center of the package, measured on the top of the component



<sup>\*</sup> slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

# Taping 9)



C63062-A1844-B3-04

## Tape and Reel 10)



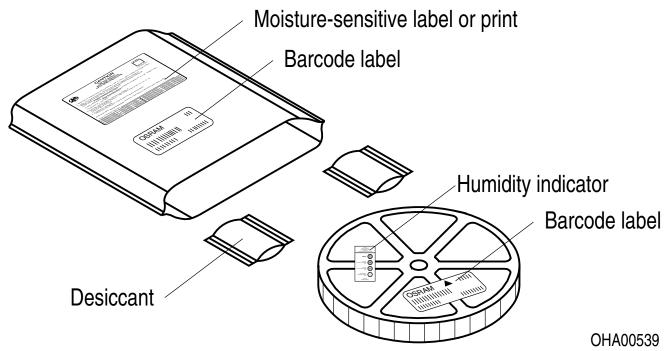
### **Reel Dimensions**

A	W		$N_{\min}$	$W_1$		$W_{2 \text{ max}}$	Pieces per PU
180 mm		8 + 0.3 / - 0.1 mm	60 mm		8.4 + 2 mm	14.4 mm	2000
330 mm		8 + 0.3 / - 0.1 mm	60 mm		8.4 + 2 mm	14.4 mm	8000

### **Barcode-Product-Label (BPL)**



## Dry Packing Process and Materials 9)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



## Type Designation System

Wavelengt  A <sub>dom</sub> typ.) A: 617 S: 633 Γ: 528 Y: 587 O: 606 G: 570 P: 560 A: 625 A: 645 V: 505  L: Lig em dio	nm super red true green yellow CG: color on demand blue CG: color on demand green color on demand lagune color on demand green color on demand lagune color on d
L	A T 6 7 6
Lead / 6: 7: T: V:	Package Properties Folded leads Feverse gullwing leads Folded leads, improved corrosion stability Folded leads, improved corrosion stability Folded leads and UX:3 w/ improved Fororosion stability (Au-LF), TiO2 jetting  Encapsulant Type / Lens Properties Folded leads and UX:3 w/ improved Fororosion stability (Au-LF), TiO2 jetting  Encapsulant Type / Lens Properties Folded leads and UX:3 w/ improved Fororosion stability (Au-LF), TiO2 jetting  Encapsulant Type / Lens Properties Folded leads Folded
	Chip Technology: 1: TSN 3: standard InGaN 4: AIGaAs 5: HOP 2000 6: Standard InGalP 9: TSN low current B: HOP 2000 C: ATON D: Small ThinGaN/ Thinfilm (e.g. 6mil) F: Thinfilm InGaAIP G: ThinGaN(Thinfilm InGaN) K: InGaAIP low current S: standard InGaN low current O: TSN



#### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



#### **Disclaimer**

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

#### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

#### Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



### Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of  $\pm 8$  % and an expanded uncertainty of  $\pm 11$  % (acc. to GUM with a coverage factor of k = 3).
- Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of  $\pm 0.05$  V and an expanded uncertainty of  $\pm 0.1$  V (acc. to GUM with a coverage factor of k = 3).
- Thermal Resistance: Rth max is based on statistic values  $(6\sigma)$ .
- <sup>6)</sup> **Thermal Resistance:** RthJA results from mounting on PC board FR 4 (pad size 16 mm² per pad)
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- <sup>8)</sup> Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- <sup>10)</sup> **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



### LY T676

Revision History				
Version	Date	Change		
1.4	2022-02-02	Characteristics Electro - Optical Characteristics (Diagrams) Dimensions of Transportation Box Schematic Transportation Box Features		



Published by OSRAM Opto Semiconductors GmbH EU RoHS and China RoHS compliant product Leibnizstraße 4, D-93055 Regensburg www.osram-os.com © All Rights Reserved.

此产品符合欧盟 RoHS 指令的要求;

按照中国的相关法规和标准,不含有毒有害物质或元素。

